

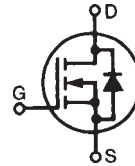
PolarHT™ HiPerFET Power MOSFET

IXFH 96N15P
IXFV 96N15P
IXFV 96N15PS

$V_{DSS} = 150$ V
 $I_{D25} = 96$ A
 $R_{DS(on)} = 24$ mΩ
 $t_{rr} < 200$ ns

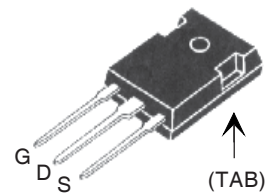
N-Channel Enhancement Mode

Preliminary Data Sheet

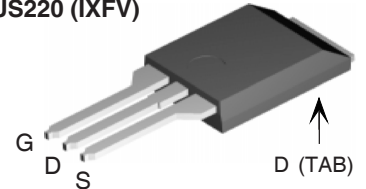


Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^{\circ}\text{C}$ to 175°C	150	V
V_{DGR}	$T_J = 25^{\circ}\text{C}$ to 175°C ; $R_{GS} = 1$ MΩ	150	V
V_{GS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	$T_C = 25^{\circ}\text{C}$	96	A
$I_{D(RMS)}$	External lead current limit	75	A
I_{DM}	$T_C = 25^{\circ}\text{C}$, pulse width limited by T_{JM}	250	A
I_{AR}	$T_C = 25^{\circ}\text{C}$	60	A
E_{AR}	$T_C = 25^{\circ}\text{C}$	40	mJ
E_{AS}	$T_C = 25^{\circ}\text{C}$	1.0	J
dv/dt	$I_S \leq I_{DM}$, $di/dt \leq 100$ A/μs, $V_{DD} \leq V_{DSS}$, $T_J \leq 175^{\circ}\text{C}$, $R_G = 4$ Ω	10	V/ns
P_D	$T_C = 25^{\circ}\text{C}$	480	W
T_J		-55 ... +175	°C
T_{JM}		175	°C
T_{stg}		-55 ... +150	°C
T_L	1.6 mm (0.062 in.) from case for 10 s Plastic body for 10s	300 250	°C °C
F_C	Mounting force	11...65/2.4...11	N/lb
M_d	Mounting torque (TO-247)	1.13/10	Nm/lb.in.
Weight	TO-247	6	g
	PLUS220	4	g

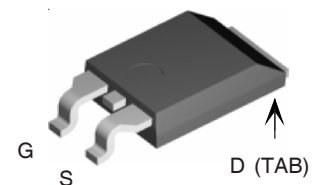
TO-247 (IXFH)



PLUS220 (IXFV)



PLUS220SMD (IXFV__S)



G = Gate D = Drain
S = Source TAB = Drain

Features

- International standard packages
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect

Advantages

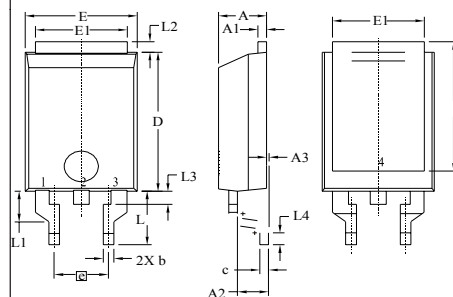
- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions ($T_J = 25^{\circ}\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
V_{DSS}	$V_{GS} = 0$ V, $I_D = 250$ μA	150		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4$ mA	3.0		5.0 V
I_{GSS}	$V_{GS} = \pm 20$ V _{DC} , $V_{DS} = 0$			±100 nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0$ V $T_J = 175^{\circ}\text{C}$			25 μA 1000 μA
$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300$ μs, duty cycle $d \leq 2\%$			24 mΩ

Symbol	Test Conditions	Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{ V}; I_D = 0.5 I_{D25}$, pulse test	35	45	S
C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1\text{ MHz}$		3500	pF
C_{oss}			1000	pF
C_{rss}			280	pF
$t_{d(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 60\text{ A}$ $R_G = 4\ \Omega$ (External)		30	ns
t_r			33	ns
$t_{d(off)}$			66	ns
t_f			18	ns
$Q_{g(on)}$	$V_{GS} = 10\text{ V}, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$		110	nC
Q_{gs}			26	nC
Q_{gd}			59	nC
R_{thJC}	(TO-247, PLUS220)		0.21	0.31 K/W
R_{thCK}				K/W

Source-Drain Diode		Characteristic Values ($T_J = 25^\circ\text{C}$, unless otherwise specified)		
Symbol	Test Conditions	Min.	typ.	Max.
I_S	$V_{GS} = 0\text{ V}$			96 A
I_{SM}	Repetitive			250 A
V_{SD}	$I_F = I_S, V_{GS} = 0\text{ V}$, Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$			1.5 V
t_{rr}	$I_F = 25\text{ A}$ $-di/dt = 100\text{ A}/\mu\text{s}$ $V_R = 100\text{ V}$		100	200 ns
Q_{RM}			600	nC
I_{RM}			6	A

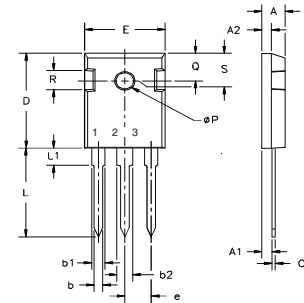
PLUS220SMD (IXFV__S) Outline



Terminals: 1 - Gate 2 - Drain
3 - Source TAB - Drain

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
A3	.000	.010	0.00	0.25
b	.035	.047	0.90	1.20
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.200BSC		5.08	BSC
L	.209	.228	5.30	5.80
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50
L4	.039	.059	1.00	1.50

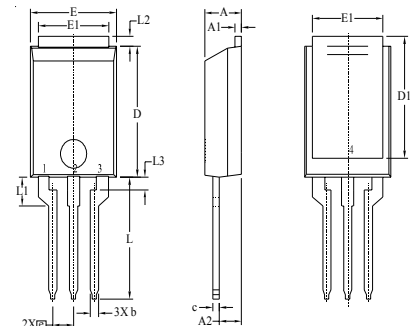
TO-247 (IXFH) Outline



Terminals: 1 - Gate 2 - Drain
3 - Source TAB - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L ₁		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

PLUS220 (IXFV) Outline



Terminals:
1 - Gate 2 - Drain
3 - Source TAB - Drain

SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.169	.185	4.30	4.70
A1	.028	.035	0.70	0.90
A2	.098	.118	2.50	3.00
b	.035	.047	0.90	1.20
c	.028	.035	0.70	0.90
D	.551	.591	14.00	15.00
D1	.512	.539	13.00	13.70
E	.394	.433	10.00	11.00
E1	.331	.346	8.40	8.80
e	.100 BSC		2.54	BSC
L	.512	.551	13.00	14.00
L1	.118	.138	3.00	3.50
L2	.035	.051	0.90	1.30
L3	.047	.059	1.20	1.50

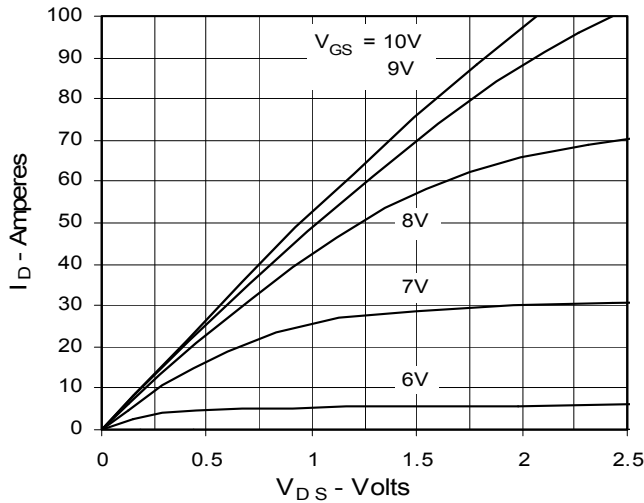
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

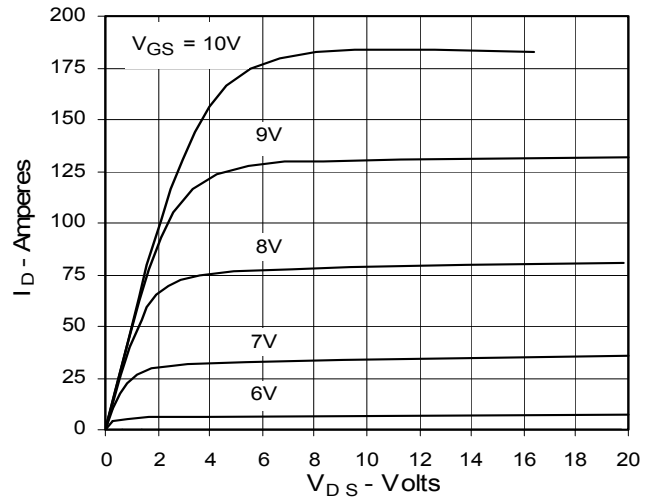
4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1
4,850,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343
4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505

6,683,344	6,727,585
6,710,405 B2	
6,710,463	

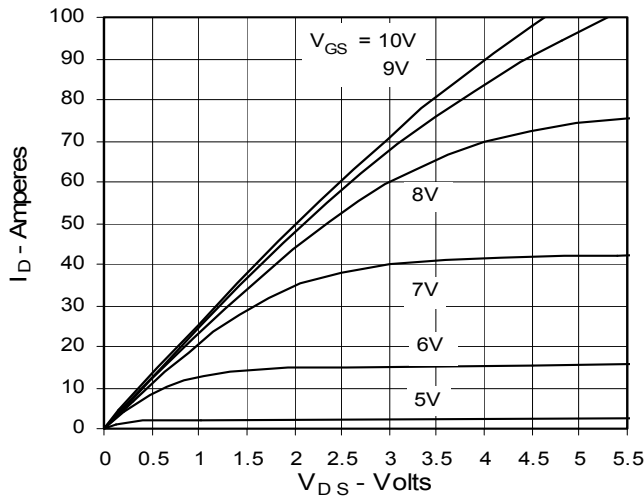
**Fig. 1. Output Characteristics
@ 25°C**



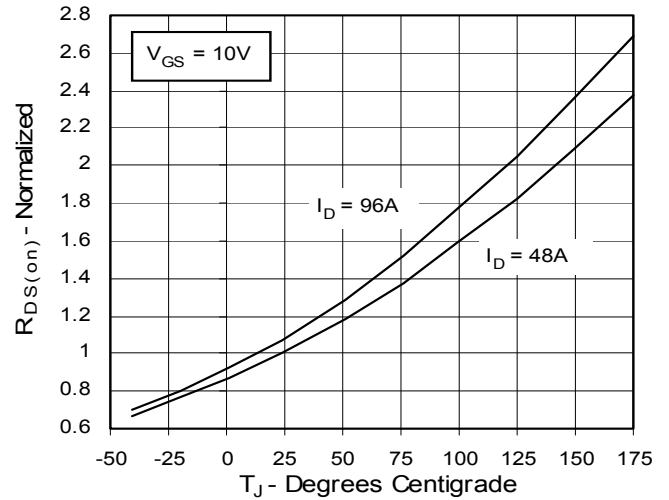
**Fig. 2. Extended Output Characteristics
@ 25°C**



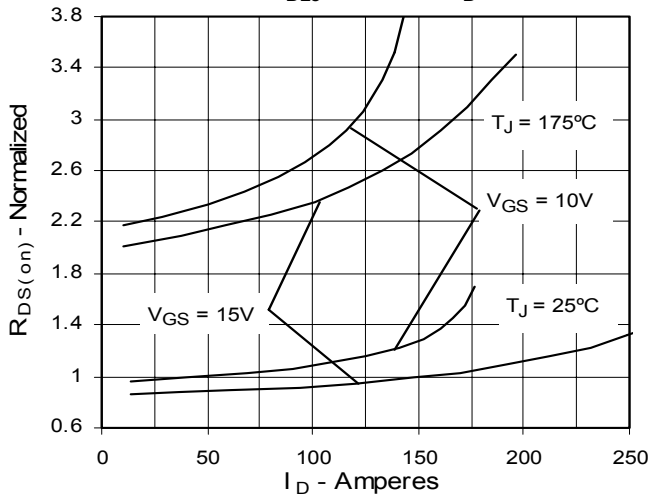
**Fig. 3. Output Characteristics
@ 150°C**



**Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25}
Value vs. Junction Temperature**



**Fig. 5. $R_{DS(on)}$ Normalized to
0.5 I_{D25} Value vs. I_D**



**Fig. 6. Drain Current vs. Case
Temperature**

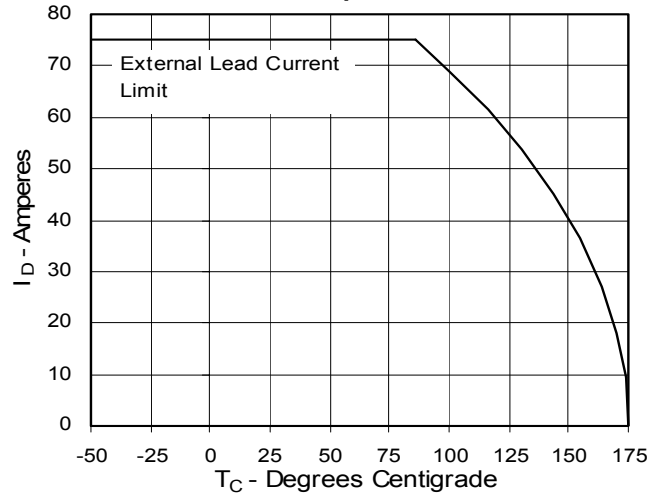


Fig. 7. Input Admittance

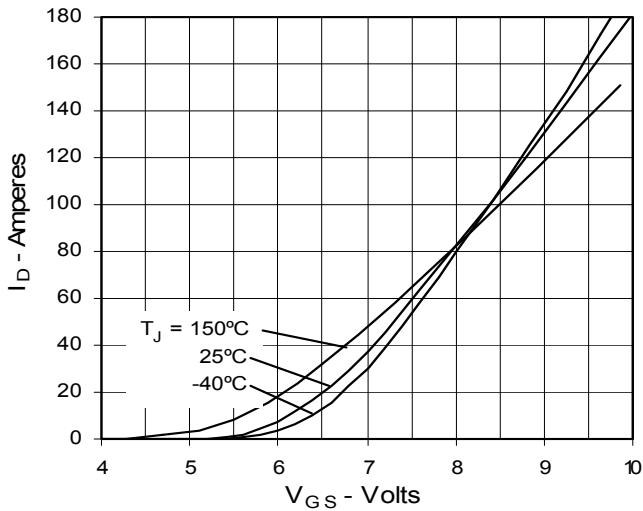


Fig. 8. Transconductance www.DataSheet4U.com

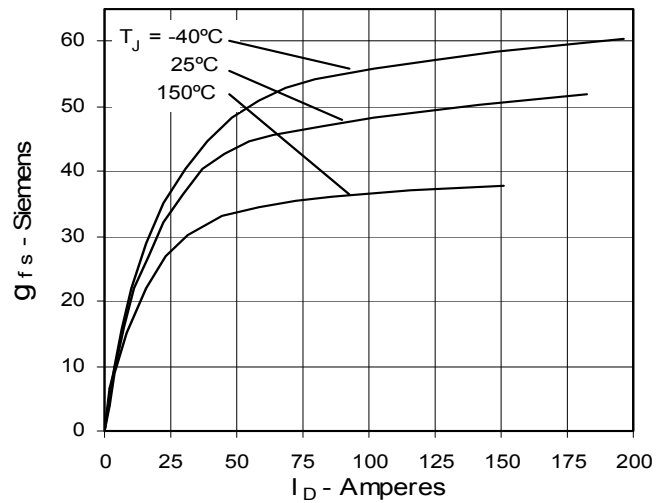


Fig. 9. Source Current vs. Source-To-Drain Voltage

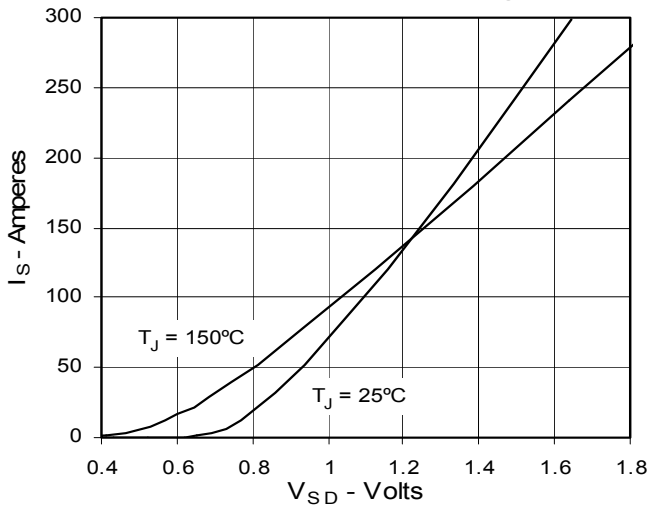


Fig. 10. Gate Charge

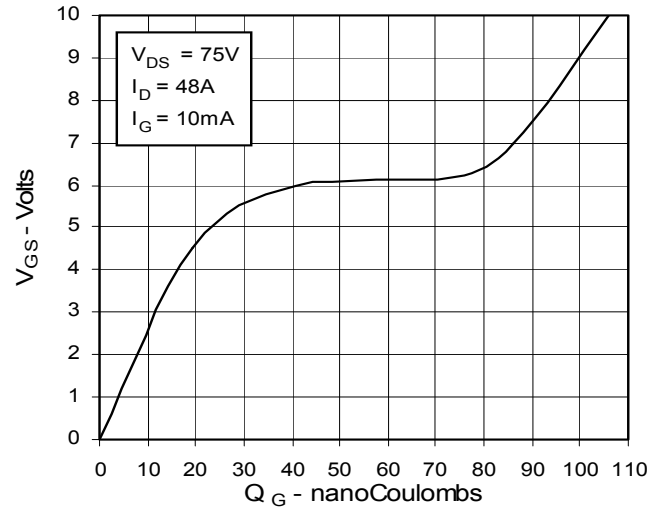


Fig. 11. Capacitance

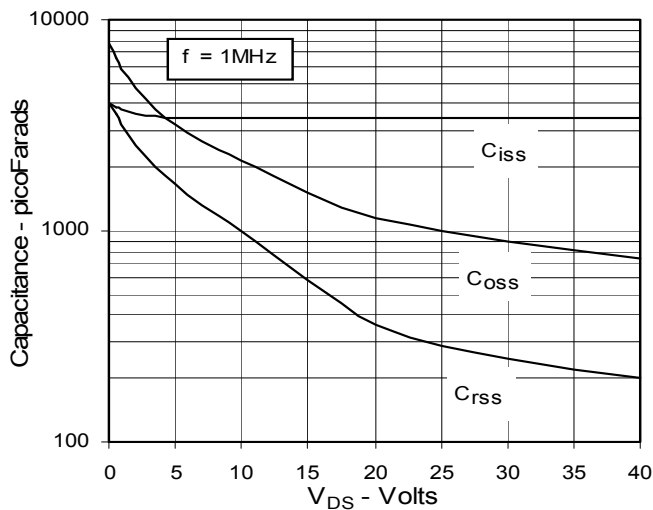


Fig. 12. Forward-Bias Safe Operating Area

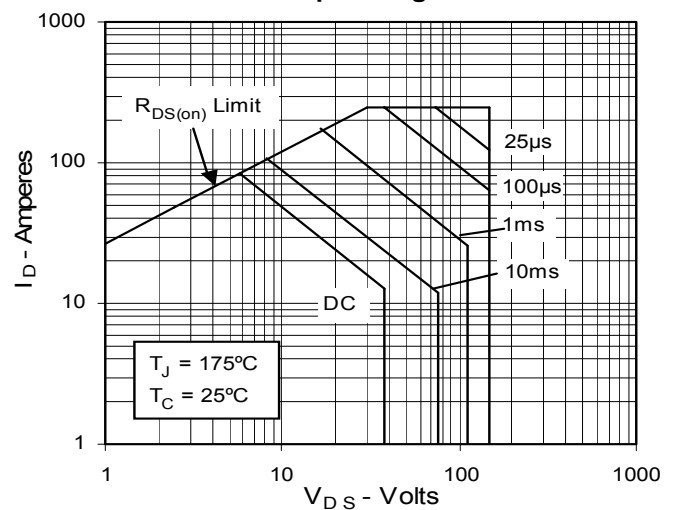


Fig. 13. Maximum Transient Thermal Resistance

